

Fullerene for semi-conducting photo- and light diodes (1.5–5.0 μm)

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Semiconducting IR photo- and light diodes for the 1.6–5.0 μm range are widely applied. They are especially required as a key component in gas analyzers for monitoring industrial and natural gases (methane, SiO_2 , NO_2 etc).

It is known that the passivation methods are developed within optoelectronics. Passivation helps prevent semiconductors from reactions with atmosphere and eliminate interface levels from the bandgap. It is known that the passivation in alcohol sulphidic solutions improves the characteristics of p – n mesodiodes and IR InAsPSb/InAs photo diodes. Though, the surfaces treated this way are unstable. We sought the solution on the way of covering the surfaces of the diodes with individual fullerene C_{70} and with an extract of higher fullerenes $\text{C}_{76} + \text{C}_{78} + \text{C}_{84} + \text{C}_{90} + \dots$. The fullerene material was obtained in "ILIP", Joint, SPb. The purity of the C_{70} fullerene was $\sim 99\%$. On the contrary, in the $\text{C}_{76} + \text{C}_{78} + \text{C}_{84} + \dots$ mix the higher fullerene content was $\sim 98\text{mas}\%$, the light fullerenes played the role of the admixture.

We grew three types of photo- and light diode structures for 2–5 μm wavelength range based on the n -type InAs (100) substrates. Liquid- and gas-phase epitaxy (MOVPE) were used. From the structures grown photodiode chips were produced with using photolithography and liquid chemical etching. Then the fullerenes, preliminarily solved in toluene, were evaporated within a drying box to form a continuous dissolved fullerene film on the solid chip surface.

The chips of $500 \times 500 \mu\text{m}^2$ obtained this way were soldered on TO-18 box. All the devices had diode type characteristics with cutoff voltage of ~ 0.4 V at RT and differential resistance of 1.0–1.2 Ohm. To determine the dark currents, reverse branches of I-V characteristic were measured before the covering, just after and the month since the procedure. When using the C_{70} fullerene as a passivating agent, the dark current for two types of the photodiodes (PD-36 and PD-46 for the 1.5–3.5 μm and 1.5–3.5 μm) reduced by 40 и 20% at standard reverse biases. In similar way, for the LED28 light diode the leak current reduced by 20%, the resistance doubled. The radiation intensity for the V-2928 light diodes at RT increased by 17–18%. Similar result was registered for ohmic power within the whole working current range.

When using the heavy fullerene mix as a passivating agent, the results are similar. The dark current reduction in the PD-36 and PD-46 were $\sim 11\%$ and 14% . Besides that, a sample temperature decrease was found (the Peltier effect).